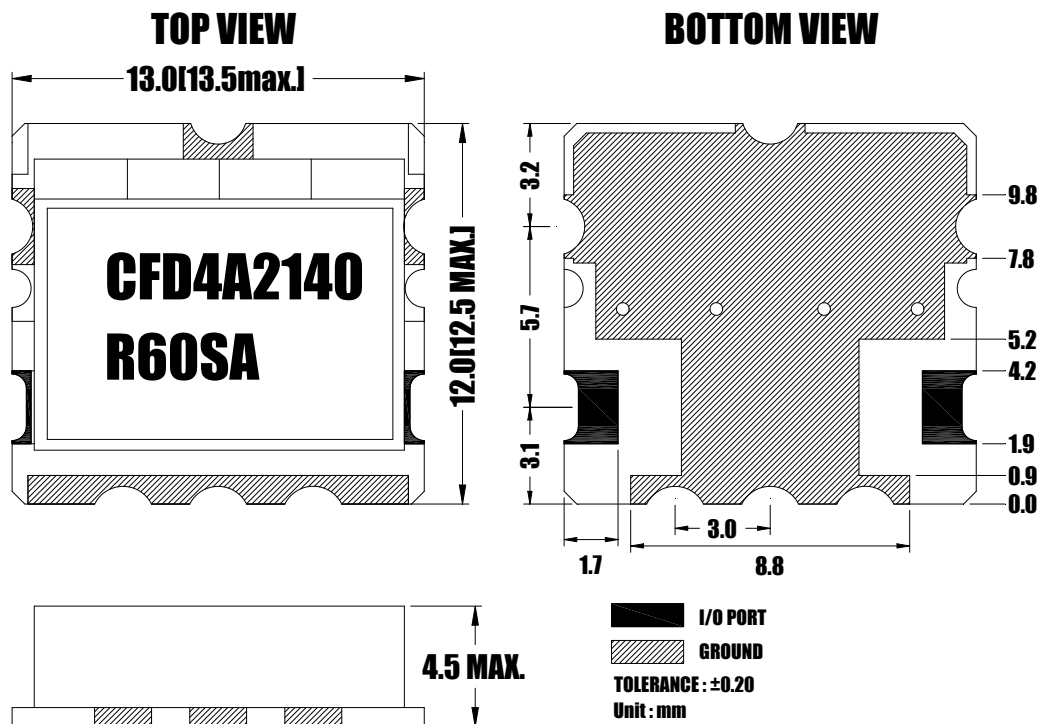


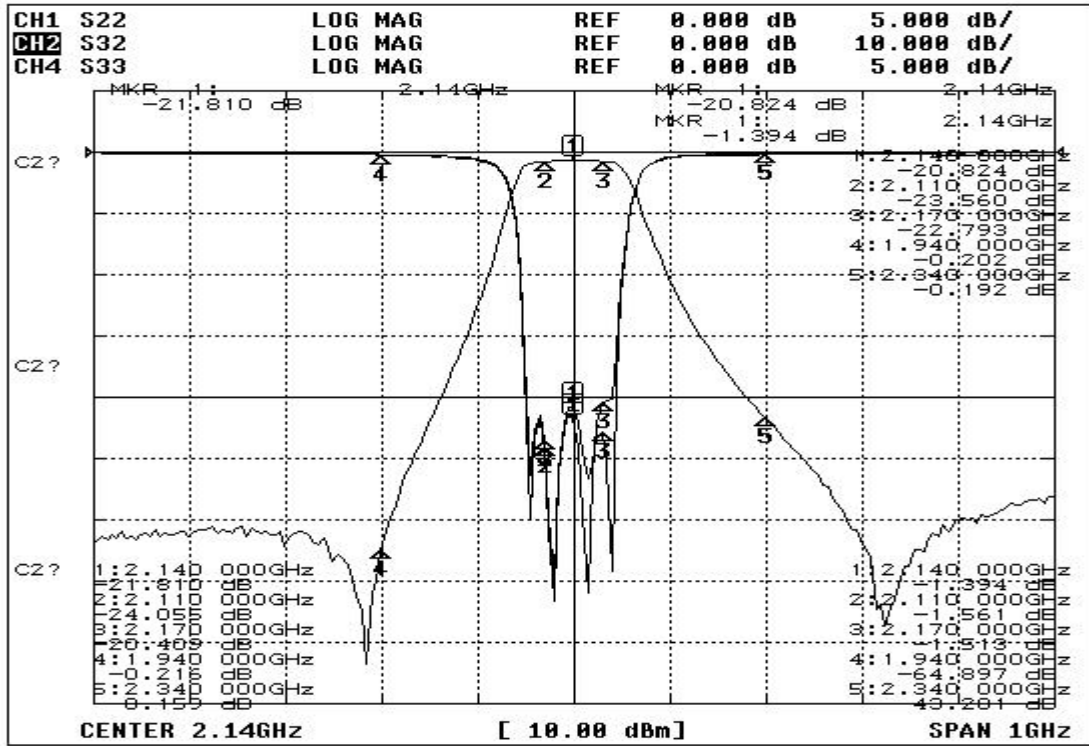
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	2140	MHz
Bandwidth [BW]	fo ±30.0 [2110 ~ 2170]	MHz
Insertion Loss in BW	2.2	dB max
Ripple in BW	0.6	dB max
Return Loss in BW	15.0	dB min
Attenuation <input type="checkbox"/> Absolute Value <input checked="" type="checkbox"/> Relative Value	40dBc min @ fo ± 200[1940~ 2140]	MHz
	35dBc min @ fo ± [4280]	MHz
	dBc min @ fo ± [~]	MHz
	dBc min @ fo ± [~]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

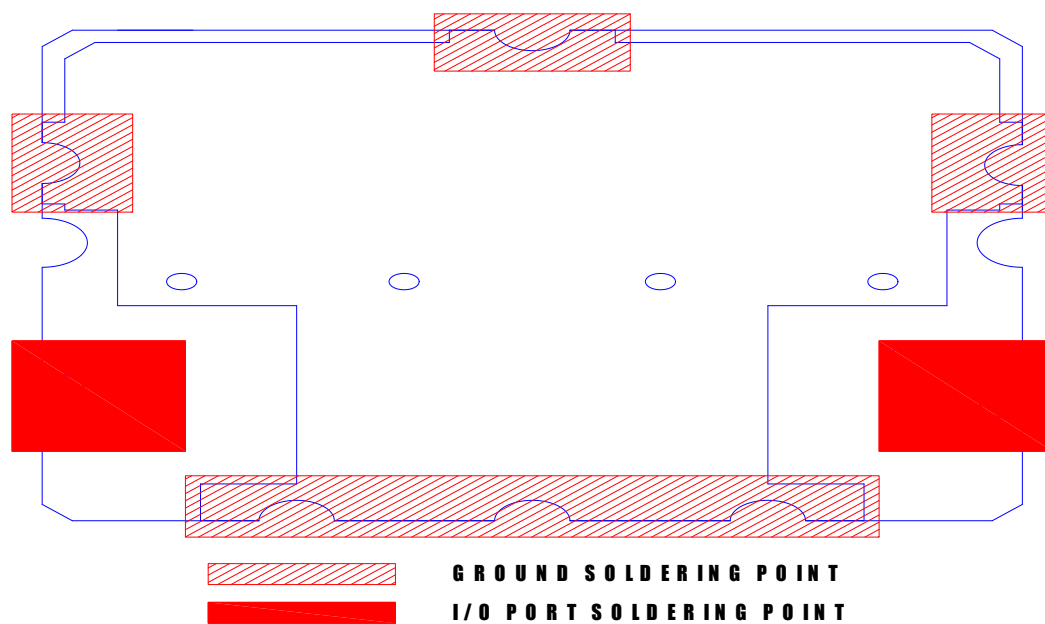
Mechanical Specification



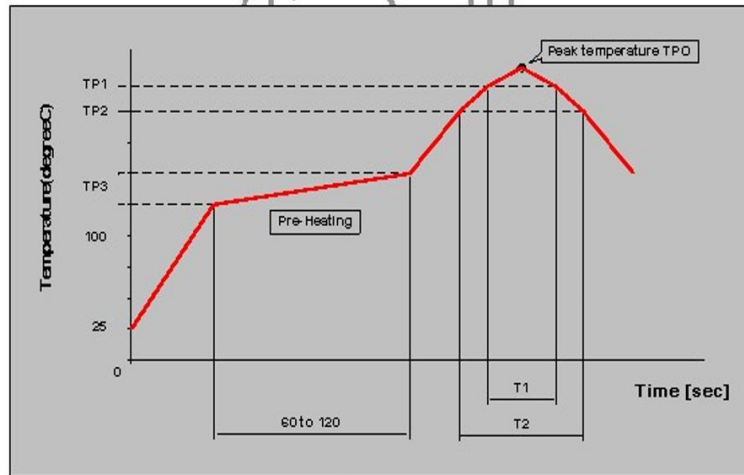
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180